

# Short Summary on Stacked DC-DC Systems

## 1 Schematics of stacked DC-DC systems

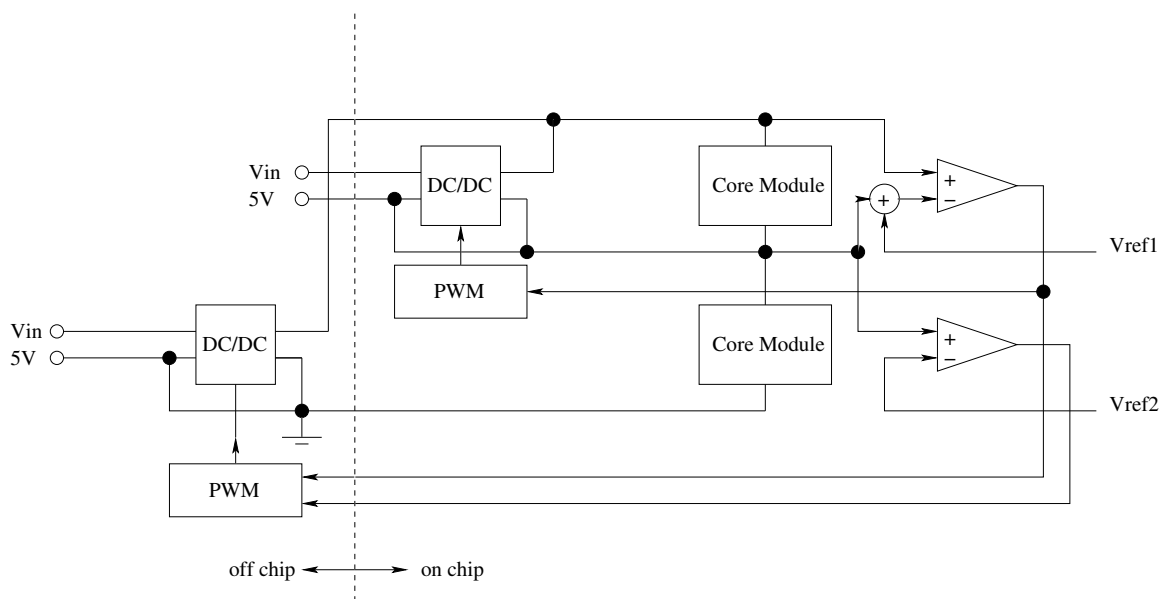


Figure 1: Schematic of 2-level stacked DC-DC converters

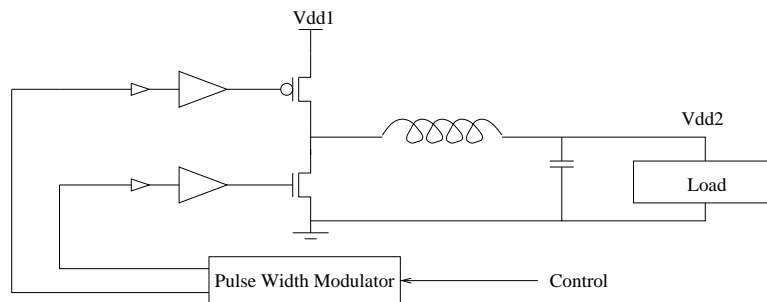


Figure 2: Schematic of Buck DC-DC converter

## 2 Determination of design parameters

### 2.1 Buck DC-DC converters

#### 2.1.1 zero voltage switching

Zero voltage switching (ZVS) means that the internal point of DC-DC converters switches under a zero voltage. [1] has detailed description on how to achieve zero voltage switching. My experiment results show that under 5MHz operation frequency, without ZVS results in an over 15% additional power loss. It also increases with the operation frequency. Therefore, ZVS is critical if we want to use high operation frequency to reduce the area of LC filter.

#### 2.1.2 Output voltage ripple

According to [2], the current ripple on the inductor and voltage ripple on the capacitor are

$$\Delta i = \frac{(V_{DD1} - V_{DD2})D}{2Lf_s} \quad (1)$$

and

$$\Delta V_{DD2} = \frac{(V_{DD1} - V_{DD2})D}{16LCf_s^2} = \frac{\Delta i}{8Cf_s} \quad (2)$$

, respectively, where  $L$  is the filter inductance,  $C$  is the filter capacitance,  $f_s$  is the switching frequency, and  $D$  is the duty cycle. This formulas have been verified by SPICE simulations.

#### 2.1.3 Power efficiency

The efficiency of a buck converter is

$$\eta = 100 \times \frac{P_{load}}{P_{load} + P_{buck}} \quad (3)$$

where  $P_{buck}$  is the average total internal power consumption of a buck conversion, which could be approximated by the total power loss of two power transistors. The total power loss of a MOSFET is a combination of conduction losses and dynamic switching losses, i.e.,

$$P_{MOS} = i_{rms}^2 R + \frac{\alpha}{\alpha - 1} (C_{ox} + C_{gs} + 2C_{gd} + C_{db}) V_{DD1}^2 f_s, \quad (4)$$

where  $R$  is the equivalent resistance of the transistor,  $i_{rms}$  is the root mean square current passing through the MOSFET,  $\alpha$  is the tapering factor of the power MOSFET gate drivers,  $C_{ox}$ ,  $C_{gs}$ ,  $C_{gd}$  and  $C_{db}$  are the gate oxide, gate-to-source overlap, gate-to-drain overlap and drain-to-body junction capacitances, respectively. The equivalent resistance of the transistor can be calculated as

$$R = \frac{1}{\mu_n C_{ox} (V_{DD1} - V_{th})} \cdot \frac{L}{W}, \quad (5)$$

where  $\mu_n$  is the electron mobility with a typical value of  $0.05m^2V^{-1}s^{-1}$ , and

$$C_{ox} = \frac{\epsilon_0 \epsilon_{SiO_2}}{T_{ox}} \quad (6)$$

$$= \frac{8.854 \cdot 10^{-14} \cdot 3.9}{2.5 \cdot 10^{-9}} \quad (7)$$

$$= 1.38 \times 10^{-4} (F/m^2) \quad (8)$$

Here, we use 100nm generation and assume  $T_{ox}$  equals to  $2.5 \cdot 10^{-9}m$ .

## 2.2 Stacked buck DC-DC converters

### 2.2.1 Output voltage ripple

### 2.2.2 Power efficiency

## References

- [1] A. Stratakos, S. Sanders, and R. Brodersen, "A low-voltage cmos dc-dc converter for a portable battery-operated system," in *Power Electronics Specialists Conference, PESC '94 Record., 25th Annual IEEE*, June 20-25, 1994, pp. pp. 619–626.
- [2] V. Kursun, S. Narendra, V. De, and E. Friedman, "Analysis of buck converters for on-chip integration with a dual supply voltage microprocessor," vol. 11, no. 3, pp. 514 – 522, June 2003.